INTEGRATED CIRCUITS

DATA SHEET

SA5212A

Transimpedance amplifier (140MHz)

Product specification
Replaces datasheet NE/SA/SE5212A of 1995 Apr 26
IC19 Data Handbook





Transimpedance amplifier (140MHz)

SA5212A

DESCRIPTION

The SA5212A is a $14 \mathrm{k}\Omega$ transimpedance, wideband, low noise differential output amplifier, particularly suitable for signal recovery in fiber optic receivers and in any other applications where very low signal levels obtained from high-impedance sources need to be amplified.

FEATURES

Extremely low noise: 2.5pA/√Hz

Single 5V supply

Large bandwidth: 140MHz

Differential outputs

Low input/output impedances

14kΩ differential transresistance

ESD hardened

APPLICATIONS

- Fiber-optic receivers, analog and digital
- Current-to-voltage converters

PIN CONFIGURATION

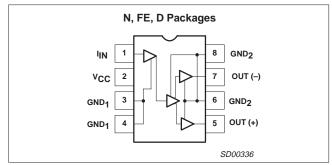


Figure 1. Pin Configuration

- Wideband gain block
- Medical and scientific instrumentation
- Sensor preamplifiers
- Single-ended to differential conversion
- Low noise RF amplifiers
- RF signal processing

ORDERING INFORMATION

DESCRIPTION	TEMPERATURE RANGE	ORDER CODE	DWG#
8-Pin Plastic Small Outline (SO) Package	-40°C to +85°C	SA5212AD	SOT96-1
8-Pin Plastic Dual In-Line Package (DIP)	-40°C to +85°C	SA5212AN	SOT97-1
8-Pin Ceramic Dual In-Line Package (DIP)	-40°C to +85°C	SA5212AFE	0580A

ABSOLUTE MAXIMUM RATINGS

SYMBOL	PARAMETER	SA5212A	UNIT
V _{CC}	Power Supply	6	V
	Power dissipation, T _A =25°C (still air) ¹		
	8-Pin Plastic DIP	1100	mW
P _{D MAX}	8-Pin Plastic SO	750	mW
	8-Pin Cerdip	750	mw
I _{IN MAX}	Maximum input current ²	5	mA
T _A	Operating ambient temperature range	-40 to 85	°C
T _J	Operating junction	-55 to 150	°C
T _{STG}	Storage temperature range	-65 to 150	°C

NOTES:

1. Maximum dissipation is determined by the operating ambient temperature and the thermal resistance:

8-Pin Plastic DIP: 110°C/W 8-Pin Plastic SO: 160°C/W

8-Pin Cerdip: 165°C/W

8-Pin Cerdip: 165°C/VV

2. The use of a pull-up resistor to V_{CC}, for the PIN diode, is recommended

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RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	RATING	UNIT
V _{CC}	Supply voltage range	4.5 to 5.5	V
T _A	Ambient temperature ranges	-40 to +85	°C
TJ	Junction temperature ranges	-40 to +105	°C

DC ELECTRICAL CHARACTERISTICS

Minimum and Maximum limits apply over operating temperature range at V_{CC} =5V, unless otherwise specified. Typical data applies at V_{CC} =5V and T_A =25°C¹.

SYMBOL	PARAMETER	TEST CONDITIONS	Min	Тур	Max	UNIT
V _{IN}	Input bias voltage		0.55	0.8	1.05	V
V _{O±}	Output bias voltage		2.5	3.3	3.8	V
V _{OS}	Output offset voltage				120	mV
I _{CC}	Supply current		20	26	33	mA
I _{OMAX}	Output sink/source current		3	4		mA
I _{IN}	Maximum input current (2% linearity)	Test Circuit 6, Procedure 2	±40	±80		μΑ
I _{N MAX}	Maximum input current overload threshold	Test Circuit 6, Procedure 4	±60	±120		μΑ

NOTES:

^{1.} As in all high frequency circuits, a supply bypass capacitor should be located as close to the part as possible.

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AC ELECTRICAL CHARACTERISTICS

Minimum and Maximum limits apply over operating temperature range at V_{CC} =5V, unless otherwise specified. Typical data applies at V_{CC} =5V and $T_A=25^{\circ}C^5$.

SYMBOL	PARAMETER	TEST CONDITIONS	Min	Тур	Max	UNIT	
R _T	Transresistance (differential output)	DC tested, R _L = ∞ Test Circuit 6, Procedure 1	9.0	14	19	kΩ	
R _O	Output resistance (differential output)	DC tested	14	30	46	Ω	
R _T	Transresistance (single-ended output)	DC tested, R _L = ∞	4.5	7	9.5	kΩ	
R _O	Output resistance (single-ended output)	DC tested	7	15	23	Ω	
f _{3dB}	Bandwidth (-3dB)	Test Circuit 1 D package, $T_A = 25^{\circ}C$ N, FE packages, $T_A = 25^{\circ}C$	100	140 120		MHz	
R _{IN}	Input resistance	IA = 20 0	70	110	150	Ω	
C _{IN}	Input capacitance		'	10	18	pF	
ΔR/ΔV	Transresistance power supply sensitivity	V _{CC} = 5 ±0.5V		9.6		%/V	
ΔR/ΔΤ	Transresistance ambient temperature sensitivity	D package ΔT _A = T _{A MAX} -T _{A MIN}		0.05		%/°C	
I _N	RMS noise current spectral density (referred to input)	Test Circuit 2 f = 10MHz T _A = 25°C		2.5		pA/√ Hz	
	Integrated RMS noise current over the band-	$T_A = 25$ °C Test Circuit 2 $\Delta f = 50$ MHz		20			
	width (referred to input) $C_S = 0^1$	$\Delta f = 100MHz$		27			
I _T		$\Delta f = 200MHz$		40		nA	
		$\Delta f = 50MHz$		22			
	$C_S = 1pF$	$\Delta f = 100MHz$					
		$\Delta f = 200MHz$		52			
PSRR	Power supply rejection ratio ²	Any package DC tested ΔV _{CC} = 0.1V Equivalent AC Test Circuit 3	20	33		dB	
PSRR	Power supply rejection ratio ² (ECL configuration)	Any package f = 0.1MHz ¹ Test Circuit 4		23		dB	
V _{O MAX}	Maximum differential output voltage swing	R _L = ∞ Test Circuit 6, Procedure 3	1.7	3.2		V _{P-P}	
V _{IN MAX}	Maximum input amplitude for output duty cycle of 50 $\pm 5\%^3$	Test Circuit 5		325		mV _{P-P}	
t _R	Rise time for 50mV output signal ⁴	Test Circuit 5		2.0		ns	

NOTES:

- 1. Package parasitic capacitance amounts to about 0.2pF.
- 2. PSRR is output referenced and is circuit board layout dependent at higher frequencies. For best performance use RF filter in V_{CC} line.
- 3. Guaranteed by linearity and over load tests.
 4. t_R defined as 20-80% rise time. It is guaranteed by -3dB bandwidth test.
- 5. As in all high frequency circuits, a supply bypass capacitor should be located as close to the part as possible.

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TEST CIRCUITS

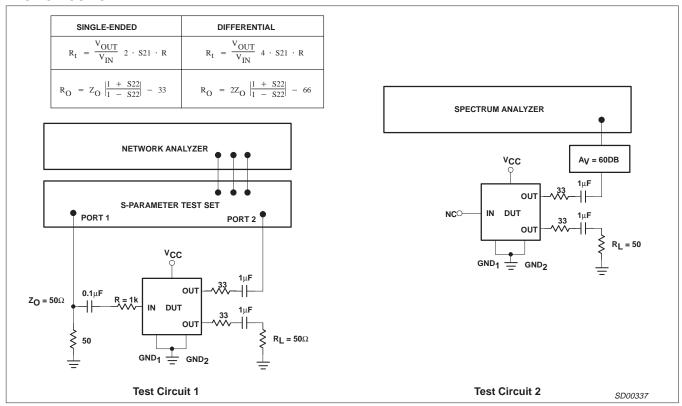


Figure 2. Test Circuits 1 and 2

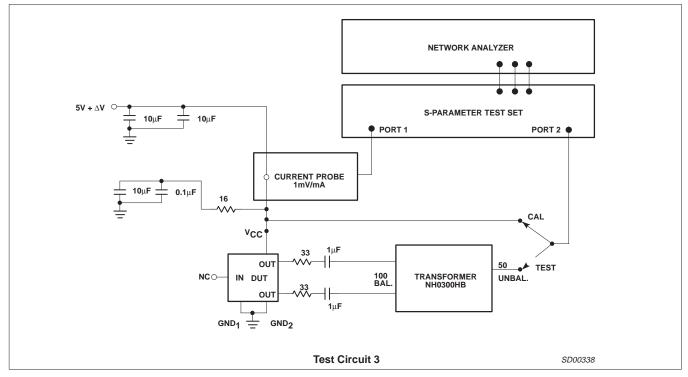


Figure 3. Test Circuit 3

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TEST CIRCUITS (Continued)

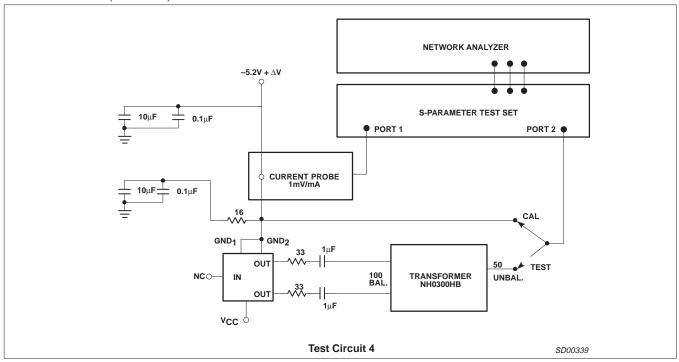


Figure 4. Test Circuit 4

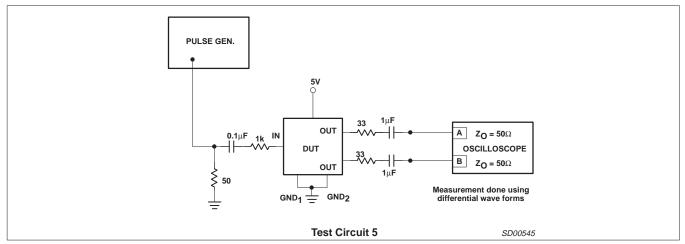


Figure 5. Test Circuit 5

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TEST CIRCUITS (Continued)

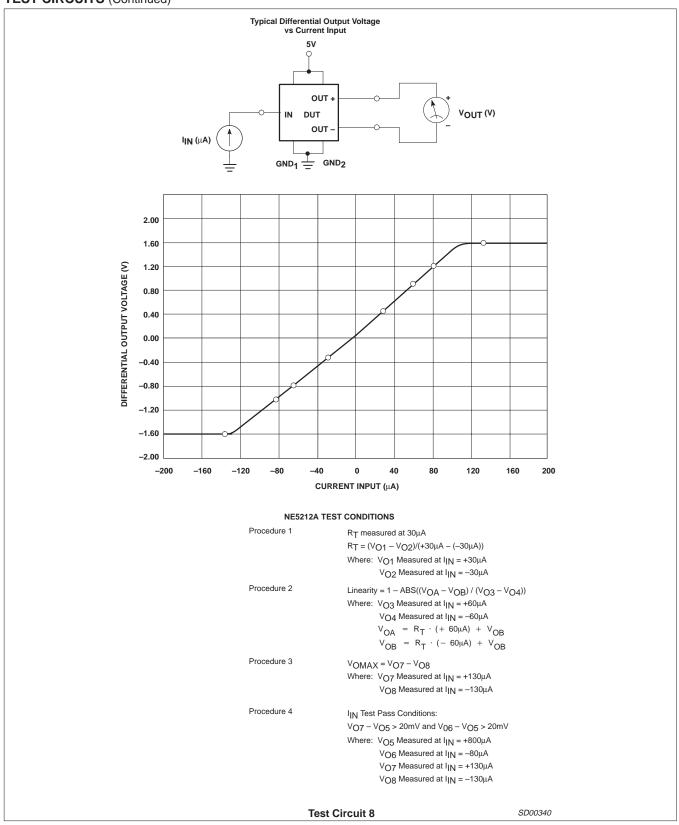


Figure 6. Test Circuit 8

TYPICAL PERFORMANCE CHARACTERISTICS

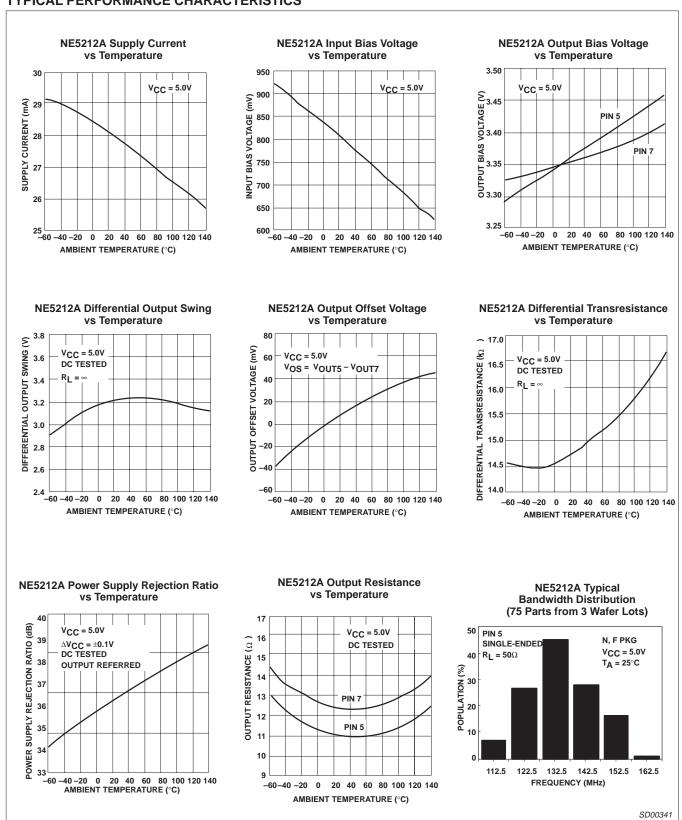


Figure 7. Typical Performance Characteristics

TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

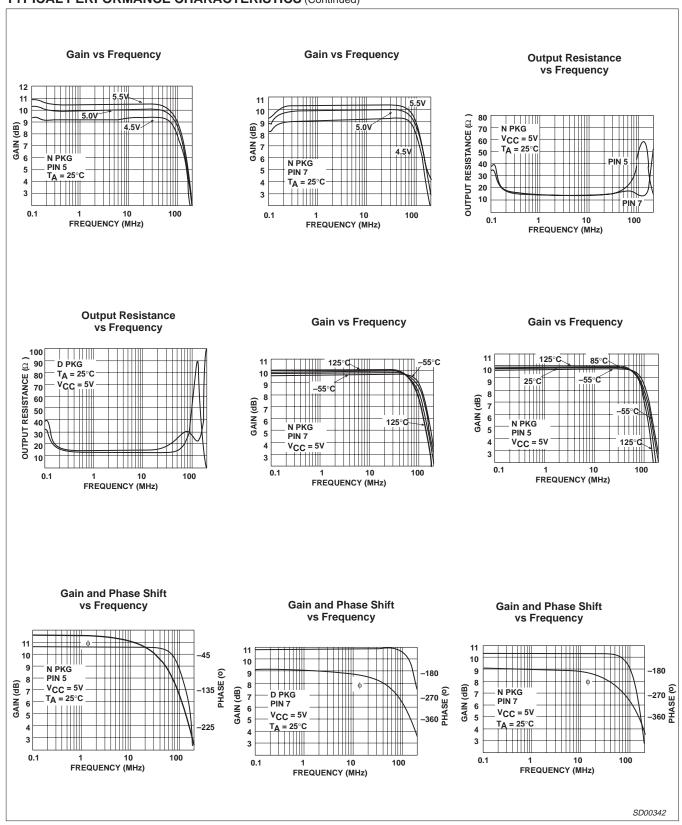


Figure 8. Typical Performance Characteristics (cont.)

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TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

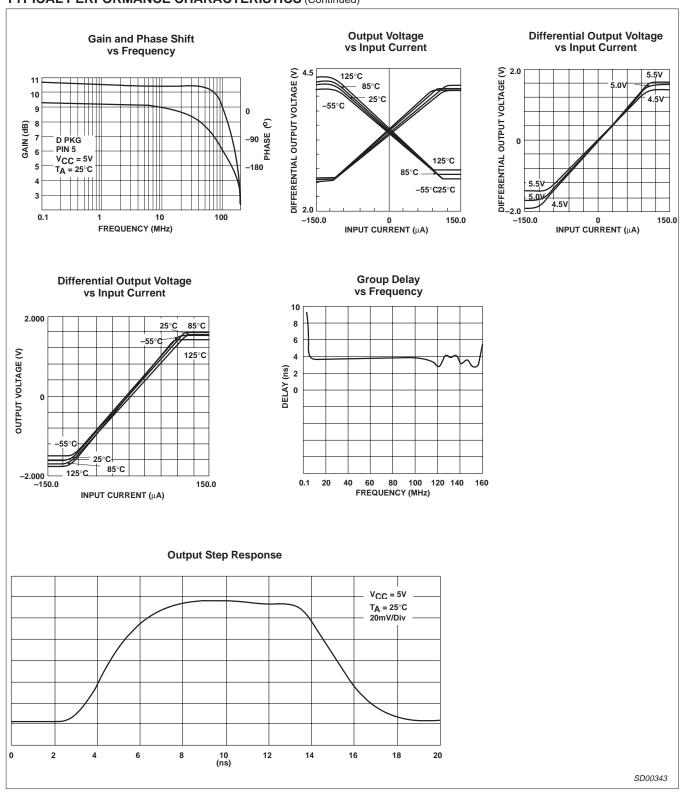


Figure 9. Typical Performance Characteristics (cont.)

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THEORY OF OPERATION

Transimpedance amplifiers have been widely used as the preamplifier in fiber-optic receivers. The SA5212A is a wide bandwidth (typically 140MHz) transimpedance amplifier designed primarily for input currents requiring a large dynamic range, such as those produced by a laser diode. The maximum input current before output stage clipping occurs at typically 240µA. The SA5212A is a bipolar transimpedance amplifier which is current driven at the input and generates a differential voltage signal at the outputs. The forward transfer function is therefore a ratio of the differential output voltage to a given input current with the dimensions of ohms. The main feature of this amplifier is a wideband, low-noise input stage which is desensitized to photodiode capacitance variations. When connected to a photodiode of a few picoFarads, the frequency response will not be degraded significantly. Except for the input stage, the entire signal path is differential to provide improved power-supply rejection and ease of interface to ECL type circuitry. A block diagram of the circuit is shown in Figure 10. The input stage (A1) employs shunt-series feedback to stabilize the current gain of the amplifier. The transresistance of the amplifier from the current source to the emitter of Q3 is approximately the value of the feedback resistor, $R_F=7k\Omega$. The gain from the second stage (A2) and emitter followers (A3 and A4) is about two. Therefore, the differential transresistance of the entire amplifier, RT is

$$R_T = \frac{V_{OUT}(diff)}{I_{IN}} = 2R_F = 2(7.2K) = 14.4k\Omega$$

The single-ended transresistance of the amplifier is typically $7.2k\Omega$.

The simplified schematic in Figure 11 shows how an input current is converted to a differential output voltage. The amplifier has a single input for current which is referenced to Ground 1. An input current from a laser diode, for example, will be converted into a voltage by the feedback resistor R_F . The transistor Q1 provides most of the open loop gain of the circuit, $A_{VOL}{\approx}70$. The emitter follower Q_2 minimizes loading on Q_1 . The transistor Q_4 , resistor R_7 , and V_{B1} provide level shifting and interface with the $Q_{15}-Q_{16}$ differential pair of the second stage which is biased with an internal reference, V_{B2} . The differential outputs are derived from emitter followers $Q_{11}-Q_{12}$ which are biased by constant current sources. The collectors of $Q_{11}-Q_{12}$ are bonded to an external pin, V_{CC2} , in order to reduce the feedback to the input stage. The output impedance is about 17Ω single-ended. For ease of performance evaluation, a 33Ω resistor is used in series with each output to match to a 50Ω test system.

BANDWIDTH CALCULATIONS

The input stage, shown in Figure 12, employs shunt-series feedback to stabilize the current gain of the amplifier. A simplified analysis can determine the performance of the amplifier. The equivalent input capacitance, C_{IN} , in parallel with the source, I_{S} , is approximately 7.5pF, assuming that $C_{\text{S}}{=}0$ where C_{S} is the external source capacitance.

Since the input is driven by a current source the input must have a low input resistance. The input resistance, R_{IN} , is the ratio of the incremental input voltage, V_{IN} , to the corresponding input current, I_{IN} and can be calculated as:

$$R_{IN} = \frac{V_{IN}}{I_{IN}} = \frac{R_F}{1 + A_{VOL}} = \frac{7.2K}{70} = 103\Omega$$

More exact calculations would yield a higher value of 110Ω .

Thus C_{IN} and R_{IN} will form the dominant pole of the entire amplifier;

$$f_{-3dB} = \frac{1}{2\pi R_{IN} C_{IN}}$$

Assuming typical values for $R_F = 7.2k\Omega$, $R_{IN} = 110\Omega$, $C_{IN} = 10pF$

$$f_{-3dB} = \frac{1}{2\pi (110) 10 \cdot 10^{-12}} = 145MHz$$

The operating point of Q1, Figure 2, has been optimized for the lowest current noise without introducing a second dominant pole in the pass-band. All poles associated with subsequent stages have been kept at sufficiently high enough frequencies to yield an overall single pole response. Although wider bandwidths have been achieved by using a cascade input stage configuration, the present solution has the advantage of a very uniform, highly desensitized frequency response because the Miller effect dominates over the external photodiode and stray capacitances. For example, assuming a source capacitance of 1pF, input stage voltage gain of 70, $R_{\rm IN}$ = 60Ω then the total input capacitance, $C_{\rm IN}$ = (1+7.5) pF which will lead to only a 12% bandwidth reduction.

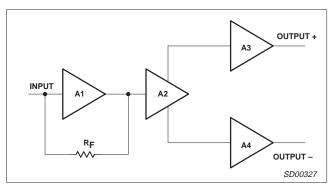


Figure 10. SA5212A - Block Diagram

NOISE

Most of the currently installed fiber-optic systems use non-coherent transmission and detect incident optical power. Therefore, receiver noise performance becomes very important. The input stage achieves a low input referred noise current (spectral density) of $3.5 p A \sqrt{\text{Hz}}$. The transresistance configuration assures that the external high value bias resistors often required for photodiode biasing will not contribute to the total noise system noise. The equivalent input $_{RMS}$ noise current is strongly determined by the quiescent current of Q_1 , the feedback resistor R_{F} , and the bandwidth; however, it is not dependent upon the internal Miller-capacitance. The measured wideband noise was 52nA RMS in a 200MHz bandwidth.

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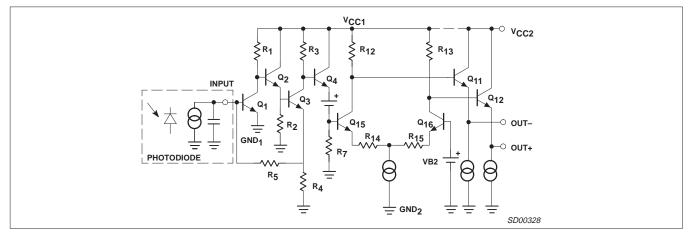


Figure 11. Transimpedance Amplifier

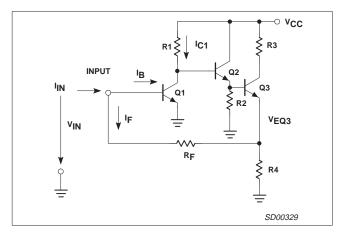


Figure 12. Shunt-Series Input Stage

DYNAMIC RANGE

The electrical dynamic range can be defined as the ratio of maximum input current to the peak noise current:

Electrical dynamic range, DE, in a 200MHz bandwidth assuming I_{INMAX} = 120 μ A and a wideband noise of I_{EQ} =52nA_{RMS} for an external source capacitance of $C_S = 1pF$.

$$D_E = \frac{\text{(Max. input current)}}{\text{(Peak noise current)}}$$

$$\begin{split} D_E(dB) &= 20 log \frac{(120 \cdot 10^{-6})}{(\sqrt{2} 52 nA)} \\ D_E(dB) &= 20 log \frac{(120 \mu A)}{(73 nA)} &= 64 dB \end{split}$$

$$D_E(dB) = 20 \log \frac{(120 \mu A)}{(73 n A)} = 64 dE$$

In order to calculate the optical dynamic range the incident optical power must be considered.

For a given wavelength λ ;

Energy of one Photon = $\frac{hc}{\lambda}$ watt sec (Joule)

Where h=Planck's Constant = 6.6×10^{-34} Joule sec.

c = speed of light = 3×10^8 m/sec

c / λ = optical frequency

No. of incident photons/sec= where P=optical incident power

No. of incident photons/sec =
$$\frac{P}{hc}$$

where P = optical incident power

No. of generated electrons/sec = η . $\frac{h}{h}$

where η = quantum efficiency

$$= \frac{\text{no. of generated electron hole paris}}{\text{no. of incident photons}} \\ \frac{\text{P}}{\text{P}}$$

$$\therefore I = \eta \cdot \frac{\frac{P}{hc}}{\lambda} \cdot e \text{ Amps (Coulombs/sec.)}$$

where e = electron charge = 1.6×10^{-19} Coulombs

Responsivity R =
$$\frac{\frac{1}{hc}}{\frac{hc}{\lambda}}$$
 Amp/watt

$$I = P \cdot I$$

Assuming a data rate of 400 Mbaud (Bandwidth, B=200MHz), the noise parameter Z may be calculated as:1

$$Z = \frac{I_{EQ}}{qB} = \frac{52 \cdot 10^{-9}}{(1.6 \cdot 10^{-19})(200 \cdot 10^{6})} = 1625 \left(\frac{Amp}{Amp}\right)$$

where \boldsymbol{Z} is the ratio of $_{\mbox{\scriptsize RMS}}$ noise output to the peak response to a single hole-electron pair. Assuming 100% photodetector quantum efficiency, half mark/half space digital transmission, 850nm lightwave and using Gaussian approximation, the minimum required optical power to achieve 10⁻⁹ BER is:

$$P_{avMIN} = 12 \frac{hc}{\lambda} B Z = 12 (2.3 \cdot 10^{-19})$$

$$200 \cdot 10^6 \ 1625 = 897 \text{nW} = -30.5 \text{dBm},$$

where h is Planck's Constant, c is the speed of light, $\boldsymbol{\lambda}$ is the wavelength. The minimum input current to the SA5212A, at this input power is:

$$I_{avMIN} = qP_{avMIN} \frac{\lambda}{hc}$$

$$= \frac{897 \cdot 10^{-9} \cdot 1.6 \cdot 10^{-19}}{2.3 \cdot 10^{-19}}$$

$$= 624 \text{nA}$$

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Choosing the maximum peak overload current of I_{avMAX} =120 μA , the maximum mean optical power is:

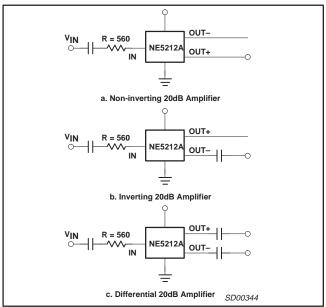


Figure 13. Variable Gain Circuit

$$\begin{split} P_{avMAX} \;\; &= \; \frac{hcI_{avMAX}}{\lambda q} = \; \frac{2.3 \, \cdot \, 10^{\, - 19} (120 \, \cdot \, 10^{\, - 6})}{1.6 \, \cdot \, 10^{\, - 19}} \\ &= 172 \mu W \; or \, - 7.6 dBm \end{split}$$

Thus the optical dynamic range, D_O is:

$$D_O = P_{avMAX} - P_{avMIN} = -30.5 - (-7.6) = 22.8 dB.$$

This represents the maximum limit attainable with the SA5212A operating at 200MHz bandwidth, with a half mark/half space digital transmission at 820nm wavelength.

APPLICATION INFORMATION

Package parasitics, particularly ground lead inductances and parasitic capacitances, can significantly degrade the frequency response. Since the SA5212A has differential outputs which can feed back signals to the input by parasitic package or board layout capacitances, both peaking and attenuating type frequency response shaping is possible. Constructing the board layout so that Ground 1 and Ground 2 have very low impedance paths has produced the best results. This was accomplished by adding a ground-plane stripe underneath the device connecting Ground 1, Pins 8-11, and Ground 2, Pins 1 and 2 on opposite ends of the SO14 package. This ground-plane stripe also provides isolation between the output return currents flowing to either V_{CC2} or Ground 2 and the input photodiode currents to flowing to Ground 1. Without this ground-plane stripe and with large lead inductances on the board, the part may be unstable and oscillate near 800MHz. The easiest way to realize that the part is not functioning normally is to measure the DC voltages at the outputs. If they are not close to their quiescent values of 3.3V (for a 5V supply), then the circuit may be oscillating. Input pin layout necessitates that the photodiode be physically very close to the input and Ground 1. Connecting Pins 3 and 5 to Ground 1 will tend to shield the input but it will also tend to increase the capacitance on the input and slightly reduce the bandwidth.

As with any high-frequency device, some precautions must be observed in order to enjoy reliable performance. The first of these is the use of a well-regulated power supply. The supply must be capable of providing varying amounts of current without significantly changing the voltage level. Proper supply bypassing requires that a good quality $0.1\mu F$ high-frequency capacitor be inserted between V_{CC1} and V_{CC2} , preferably a chip capacitor, as close to the package pins as possible. Also, the parallel combination of $0.1\mu F$ capacitors with $10\mu F$ tantalum capacitors from each supply, V_{CC1} and V_{CC2} , to the ground plane should provide adequate decoupling. Some applications may require an RF choke in series with the power supply line. Separate analog and digital ground leads must be maintained and printed circuit board ground plane should be employed whenever possible.

BASIC CONFIGURATION

A trans resistance amplifier is a current-to-voltage converter. The forward transfer function then is defined as voltage out divided by current in, and is stated in ohms. The lower the source resistance, the higher the gain. The SA5212A has a differential transresistance of $14k\Omega$ typically and a single-ended transresistance of $7k\Omega$ typically. The device has two outputs: inverting and non-inverting. The output

voltage in the differential output mode is twice that of the output voltage in the single-ended mode. Although the device can be used without coupling capacitors, more care is required to avoid upsetting the internal bias nodes of the device. Figure 13 shows some basic configurations.

VARIABLE GAIN

Figure 14 shows a variable gain circuit using the SA5212A and the SA5230 low voltage op amp. This op amp is configured in a non-inverting gain of five. The output drives the gate of the SD210 DMOS FET. The series resistance of the FET changes with this output voltage which in turn changes the gain of the SA5212A. This circuit has a distortion of less than 1% and a 25dB range, from -42.2dBm to -15.9dBm at 50MHz, and a 45dB range, from -60dBm to -14.9dBm at 10MHz with 0 to 1V of control voltage at $V_{\rm CC}$.

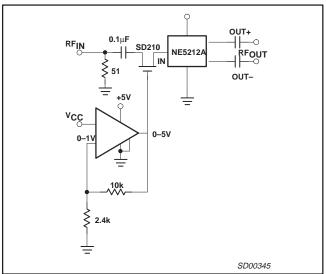


Figure 14. Variable Gain Circuit

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16MHZ CRYSTAL OSCILLATOR

Figure 15 shows a 16MHz crystal oscillator operating in the series resonant mode using the SA5212A. The non-inverting input is fed back to the input of the SA5212A in series with a 2pF capacitor. The output is taken from the inverting output.

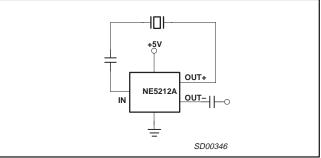


Figure 15. 16MHz Crystal Oscillator

DIGITAL FIBER OPTIC RECEIVER

Figures 16 and 17 show a fiber optic receiver using off-the-shelf components.

The receiver shown in Figure 16 uses the SA5212A, the Philips Semiconductors 10116 ECL line receiver, and Philips/Amperex BPF31 PIN diode. The circuit is a capacitor-coupled receiver and utilizes positive feedback in the last stage to provide the hysteresis. The amount of hysteresis can be tailored to the individual application by changing the values of the feedback resistors to maintain the desired balance between noise immunity and sensitivity. At room temperature, the circuit operates at 50Mbaud with a BER of 10E-10 and over the automotive temperature range at 40Mbaud with a BER of 10E-9. Higher speed experimental diodes have been used to operate this circuit at 220Mbaud with a BER of 10E-10.

Figure 17 depicts a TTL receiver using the SA5212A and the SA5214 fast amplifier system along with the Philips/Amperex PIN diode. The system shown is optimized for 50 Mb/s Non Return to Zero (NRZ) data. A link status indication is provided along with a jamming function when the input level is below a user-programmable threshold level.

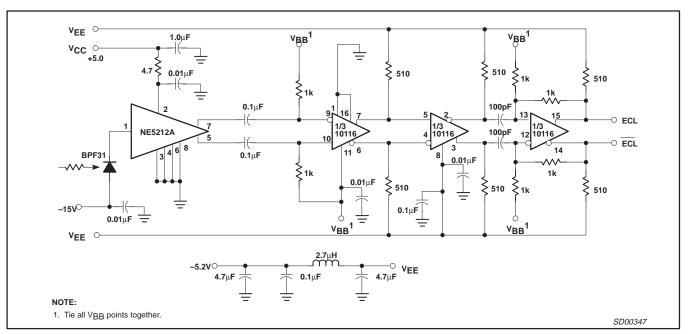


Figure 16. ECL Fiber Optic Receiver

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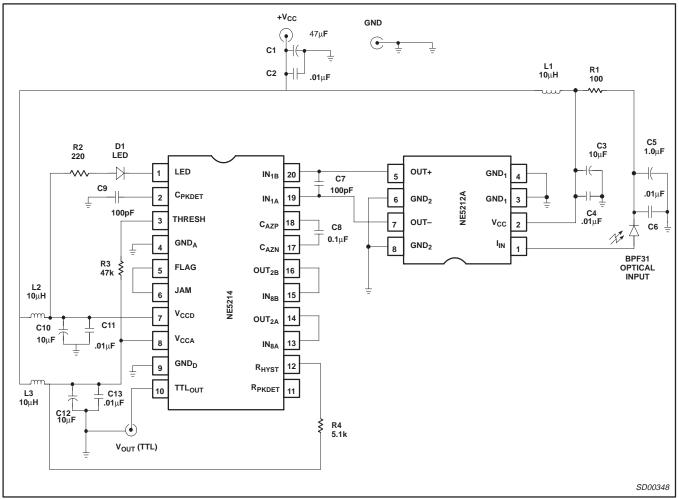


Figure 17. A 50Mb/s TTL Digital Fiber Optic Receiver

Transimpedance amplifier (140MHz)

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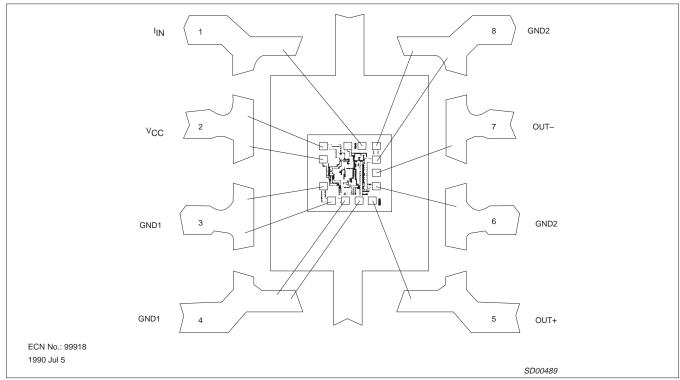


Figure 18. SA5212A Bonding Diagram

Die Sales Disclaimer

Due to the limitations in testing high frequency and other parameters at the die level, and the fact that die electrical characteristics may shift after packaging, die electrical parameters are not specified and die are not guaranteed to meet electrical characteristics (including temperature range) as noted in this data sheet which is intended only to specify electrical characteristics for a packaged device.

All die are 100% functional with various parametrics tested at the wafer level, at room temperature only (25°C), and are guaranteed to be 100% functional as a result of electrical testing to the point of wafer sawing only. Although the most modern processes are utilized for wafer sawing and die pick and place into waffle pack

carriers, it is impossible to guarantee 100% functionality through this process. There is no post waffle pack testing performed on individual die.

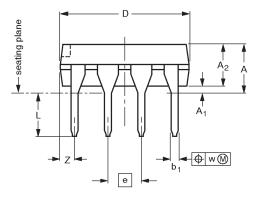
Since Philips Semiconductors has no control of third party procedures in the handling or packaging of die, Philips Semiconductors assumes no liability for device functionality or performance of the die or systems on any die sales.

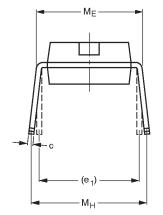
Although Philips Semiconductors typically realizes a yield of 85% after assembling die into their respective packages, with care customers should achieve a similar yield. However, for the reasons stated above, Philips Semiconductors cannot guarantee this or any other yield on any die sales.

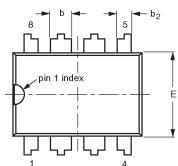
SA5212A

DIP8: plastic dual in-line package; 8 leads (300 mil)

SOT97-1









DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	b ₂	С	D ⁽¹⁾	E ⁽¹⁾	е	e ₁	L	ME	M _H	w	Z ⁽¹⁾ max.
mm	4.2	0.51	3.2	1.73 1.14	0.53 0.38	1.07 0.89	0.36 0.23	9.8 9.2	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	1.15
inches	0.17	0.020	0.13	0.068 0.045	0.021 0.015	0.042 0.035	0.014 0.009	0.39 0.36	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.045

Note

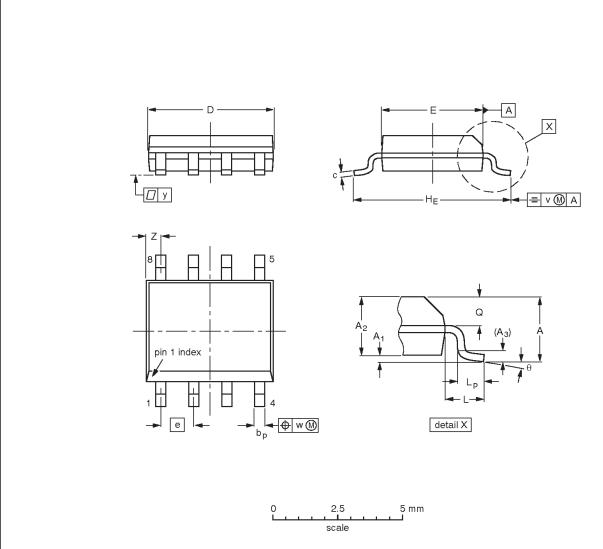
1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE	
SOT97-1	050G01	MO-001AN			92-11-17 95-02-04	

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SO8: plastic small outline package; 8 leads; body width 3.9mm

SOT96-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	Ьp	С	D ⁽¹⁾	E ⁽²⁾	е	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	5.0 4.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8°
inches	0.069	0.010 0.004	0.057 0.049	0.01		0.0100 0.0075	0.20 0.19	0.16 0.15	0.050	0.244 0.228	0.041	0.039 0.016		0.01	0.01	0.004	0.028 0.012	0°

Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT96-1	076E03S	MS-012AA			95-02-04 97-05-22

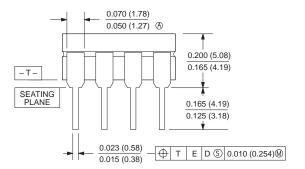
SA5212A

Transimpedance amplifier (140MHz)

0580A

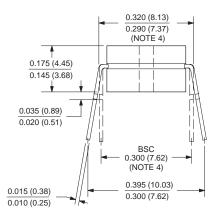
8-PIN (300 mils wide) CERAMIC DUAL IN-LINE (F) PACKAGE

0.055 (1.40) 0.055 (1.40) 0.030 (0.76) 0.030 (0.76) 0.303 (7.70) – E – 0.245 (6.22) PIN # 1 0.100 (2.54) BSC 0.408 (10.36) – D – 0.376 (9.55)



NOTES:

- Controlling dimension: Inches. Millimeters are shown in parentheses.
- 2. Dimension and tolerancing per ANSI Y14. 5M-1982.
- 3. "T", "D", and "E" are reference datums on the body and include allowance for glass overrun and meniscus on the seal line, and lid to base mismatch.
- 4. These dimensions measured with the leads constrained to be perpendicular to plane T.
- 5. Pin numbers start with Pin #1 and continue counterclockwise to Pin #8 when viewed from the top.



Transimpedance amplifier (140MHz)

SA5212A

Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
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^[1] Please consult the most recently issued datasheet before initiating or completing a design.

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